

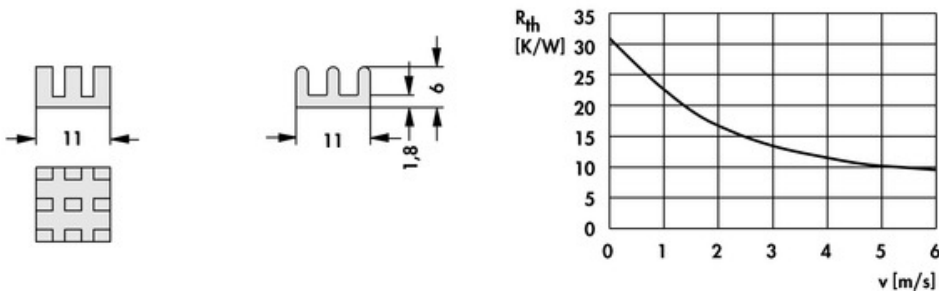
Data sheet Product ICK BGA 11 x 11 x 6

Heatsinks and active heatsinks for processors>Heatsinks for BGAs
11 x 11 x 6 mm, for IC design BGA and others

Features

way of fixation:	<ul style="list-style-type: none"> • therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	11 mm
height:	6 mm
plate thickness:	1.8 mm
length:	11 mm
thermal resistance:	31 - 9 K/W
dissipation loss:	1.9 W
surface:	black anodised

Technical Drawing



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